FAIRCHILD
SEMICONDUCTOR ™

FDN340P

February 2007

FDN340P

Single P-Channel, Logic Level, PowerTrench® MOSFET

General Description

This P-Channel Logic Level MOSFET is produced using Fairchild Semiconductor advanced Power Trench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices are well suited for portable electronics applications: load switching and power management, battery charging circuits, and DC/DC conversion.

Features

- –2A, 20 V $R_{DS(ON)}$ = 70 mΩ @ V_{GS} = –4.5 V
  $R_{DS(ON)}$ = 110 mΩ @ V_{GS} = –2.5 V

- Low gate charge (7.2 nC typical).

- High performance trench technology for extremely low $R_{DS(ON)}$.

- High power version of industry Standard SOT-23 package. Identical pin-out to SOT-23 with 30% higher power handling capability.

SuperSOT -3 ™

D

G   S
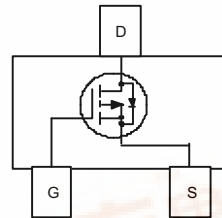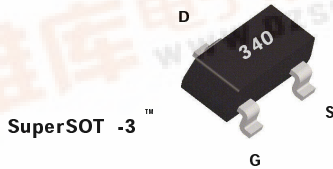
Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		–20	V
V_{GSS}	Gate-Source Voltage		±8	V
I_D	Drain Current – Continuous	(Note 1a)	–2	A
	– Pulsed		–10	
P_D	Power Dissipation for Single Operation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		–55 to +150	°C

Thermal Characteristics

$R_{θJA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
$R_{θJC}$	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
340	FDN340P	7''	8mm	3000 units

Electrical Characteristics

$T_A = 25°C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0$ V, $I_D = -250$ µA	−20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250$ µA, Referenced to 25°C		−12		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16$ V, $V_{GS} = 0$ V			−1	µA
		$V_{DS} = -16$ V, $V_{GS} = 0$ V, T_J=55°C			−10	
I_{GSSF}	Gate–Body Leakage, Forward	$V_{GS} = 8$ V, $V_{DS} = 0$ V			100	nA
I_{GSSR}	Gate–Body Leakage, Reverse	$V_{GS} = -8$ V, $V_{DS} = 0$ V			−100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = -250$ µA	−0.4	−0.8	−1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250$ µA, Referenced to 25°C		3		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = -4.5$ V, $I_D = -2$ A		60	70	mΩ
		$V_{GS} = -4.5$ V, $I_D = -2$ A, T_J=125°C		77	120	
		$V_{GS} = -2.5$ V, $I_D = -1.7$A,		82	110	
$I_{D(on)}$	On–State Drain Current	$V_{GS} = -4.5$ V, $V_{DS} = -5$ V	−5			A
g_{FS}	Forward Transconductance	$V_{DS} = -4.5$ V, $I_D = -2$ A		9		S
Dynamic Characteristics						
600	Input Capacitance	$V_{DS} = -10$ V, $V_{GS} = 0$ V,		779		pF
175	Output Capacitance	f = 1.0 MHz		121		pF
80	Reverse Transfer Capacitance			56		pF
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = -10$ V, $I_D = -1$ A,		10	20	ns
t_r	Turn–On Rise Time	$V_{GS} = -4.5$ V, $R_{GEN} = 6$ Ω		9	10	ns
$t_{d(off)}$	Turn–Off Delay Time			27	43	ns
t_f	Turn–Off Fall Time			11	20	ns
Q_g	Total Gate Charge	$V_{DS} = -10$V, $I_D = -3.5$ A,		7.2	10	nC
Q_{gs}	Gate–Source Charge	$V_{GS} = -4.5$ V		1.7		nC
Q_{gd}	Gate–Drain Charge			1.5		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain–Source Diode Forward Current				−0.42	A
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0$ V, $I_S = -0.42$ A (Note 2)		−0.7	−1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a. 250°C/W when mounted on a 0.02in^2 pad of 2 oz copper

b. 270°C/W when mounted on a .001 in^2 pad of 2 oz copper

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%
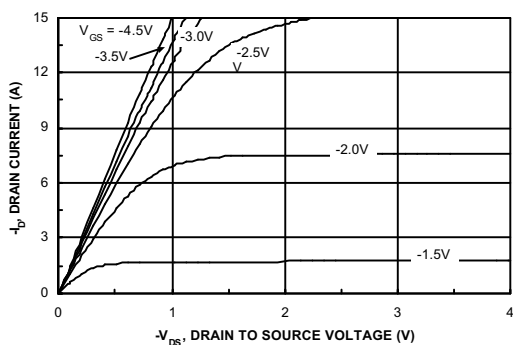
Typical Characteristics

Figure 1. On-Region Characteristics.
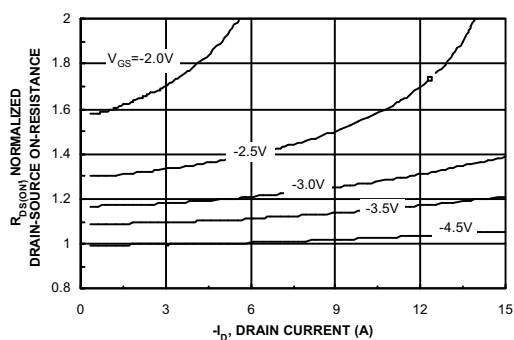

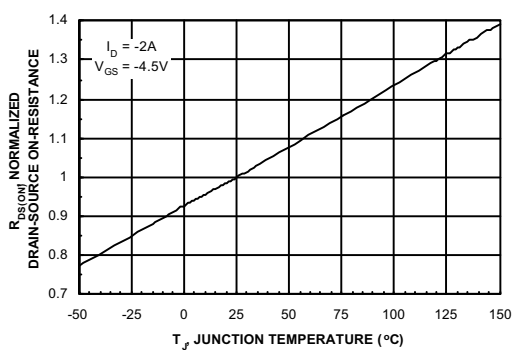**Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.**

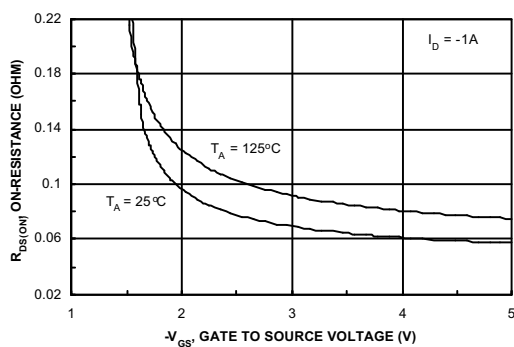**Figure 3. On-Resistance Variation with Temperature.**

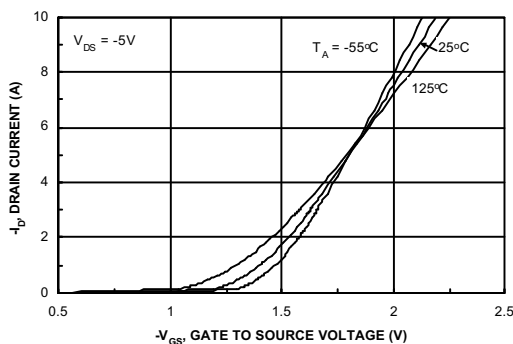**Figure 4. On-Resistance Variation with Gate-to-Source Voltage.**

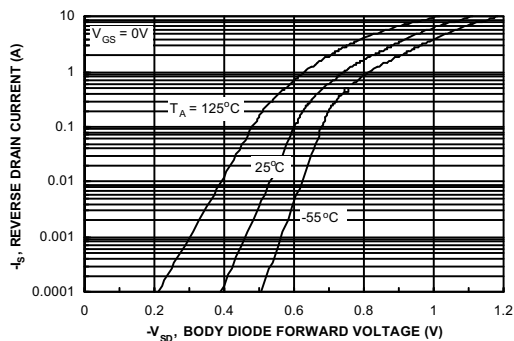**Figure 5. Transfer Characteristics.**

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.
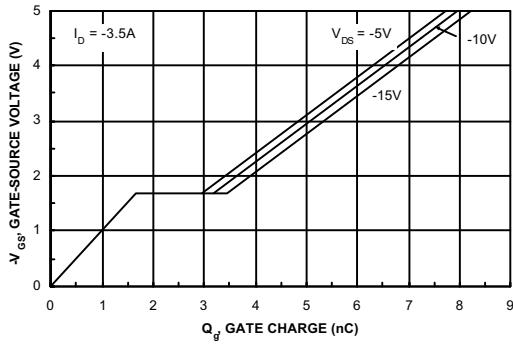
Typical Characteristics
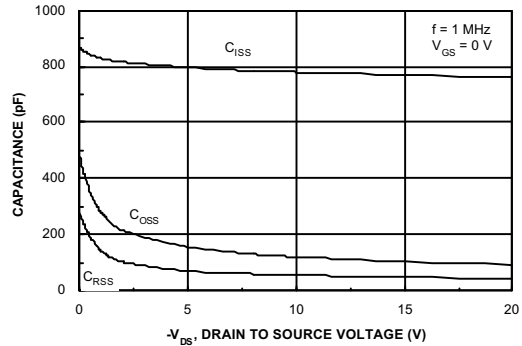

Figure 7. Gate Charge Characteristics.
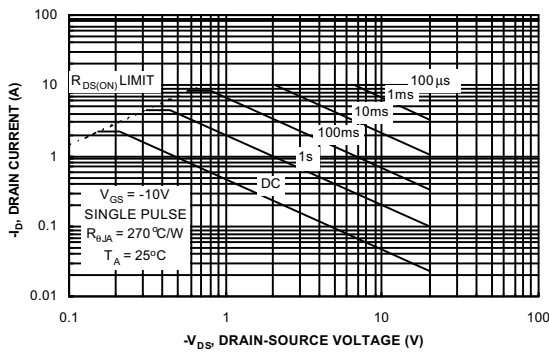

Figure 8. Capacitance Characteristics.

Figure 9. Maximum Safe Operating Area.
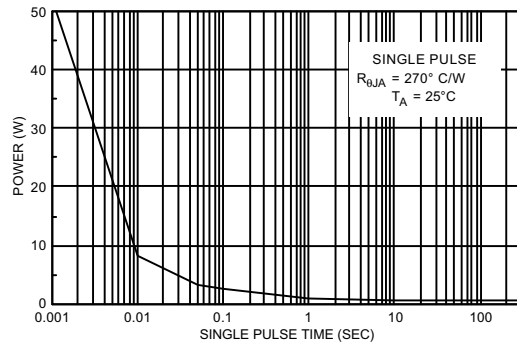
Figure 10. Single Pulse Maximum
Power Dissipation.

$$R_{\theta JA}(t) = r(t) * R_{\theta JA}$$
$$R_{\theta JA} = 270 \text{ °C/W}$$

$$T_J - T_A = P * R_{\theta JA}(t)$$
$$\text{Duty Cycle, } D = t_1 / t_2$$
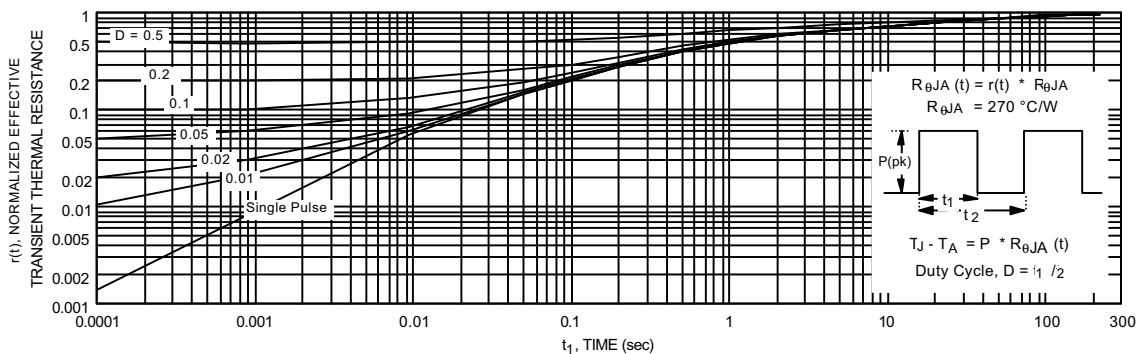
Figure 11. Transient Thermal Response Curve.

**Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.**

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FACT Quiet Series™	OCX™	SILENT SWITCHER®	UniFET™
ActiveArray™	GlobalOptoisolator™	OCXPro™	SMART START™	VCX™
Bottomless™	GTO™	OPTOLOGIC®	SPM™	Wire™
Build it Now™	HiSeC™	OPTOPLANAR™	Stealth™	
CoolFET™	I^2C™	PACMAN™	SuperFET™	
CROSSVOLT™	*i-Lo*™	POP™	SuperSOT™-3	
DOME™	ImpliedDisconnect™	Power247™	SuperSOT™-6	
EcoSPARK™	IntelliMAX™	PowerEdge™	SuperSOT™-8	
E^2CMOS™	ISOPLANAR™	PowerSaver™	SyncFET™	
EnSigna™	LittleFET™	PowerTrench®	TCM™	
FACT®	MICROCOUPLER™	QFET®	TinyBoost™	
FAST®	MicroFET™	QS™	TinyBuck™	
FASTr™	MicroPak™	QT Optoelectronics™	TinyPWM™	
FPS™	MICROWIRE™	Quiet Series™	TinyPower™	
FRFET™	MSX™	RapidConfigure™	TinyLogic®	
	MSXPro™	RapidConnect™	TINYOPTO™	
Across the board. Around the world.™		μSerDes™	TruTranslation™	
The Power Franchise®		ScalarPump™	UHC®	
Programmable Active Droop™				

DISCLAIMER
FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS
Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. I22